

Item	Qty	Ref.	Type	Part Name	Manufacturer	Value	Package	Manufacturer	Description
1	1	C1	Ceramic	C2012X7R2A104	TDK	0.1uF,100V	805		Capacitor, Ceramic, 0.1uF, 100V, 10%, 0805
2	2	C2 C10	Ceramic	C3225X7R2A225	TDK	2.2uF, 100V	1210		Capacitor, Ceramic, 2.2uF, 100V, 1210
3	1	C4	Ceramic	std	std	0.01uF	603		Capacitor, Ceramic, 0.01uF, 50V, 10%, 0603
4	1	C5	Ceramic	std	std	1u	603		Capacitor, Ceramic, 1uF, 16V, 10%, 0603
5	2	C6 C3	Ceramic	C3225X7R1E106	TDK	10uF,25V	1210		Capacitor, Ceramic, 10uF, 25V, 1210
6	1	C8	Ceramic	C2012X7R2A104	TDK	0.1u,100v	805		Capacitor, Ceramic, 0.1uF, 100V, 10%, 0805
7	1	C9	Ceramic	std	std	1nF	603		Capacitor, Ceramic, 1nF, 50V, 10%, 0603
8	1	C7	Ceramic	C2012C0G2A472	TDK	4.7nF,100v	805		Capacitor, Ceramic, 0.1uF, 100V, 5%, 0805
9	1	L1	inductor	MSD1260T-224KL	Corecraft	220uH	XL		
10	1	D2	schotty	NA	ON	2A,100V	SMA	NA	
11	1	D3	schotty	MBRA2H100CTG	ON	2A,100V	SMA		Diode,schotty, 2A, 100V, SMA
12	1	D4	Switching diode	MMDL914T1G		0.2A,100V	SOD323		Switching diode, 0.2A,100V, SOD323
13	1	U2	Buck controller	LM5006MM	TI		MSOP-10		
14	1	R1	Resistor	Resistor	Std	300k	805		Resistor, Chip, 300K, 1/5W, 1%, 0805
15	1	R2	Resistor	Resistor	Std	51K	603		Resistor, Chip, 51K, 1/8W, 1%, 0603
16	1	R3	Resistor	Resistor	Std	51k	603		Resistor, Chip, 51K, 1/8W, 1%, 0603
17	1	R4	Resistor	Resistor	Std	430K	805		Resistor, Chip, 430k, 1/5W, 1%, 0805
18	1	R5	Resistor	Resistor	Std	51K	603		Resistor, Chip, 47K, 1/8W, 1%, 0603
19	1	R6	Resistor	Resistor	Std	75K	603		Resistor, Chip, 30K, 1/8W, 1%, 0603
20	1	R7	Resistor	Resistor	Std	15K	603		Resistor, Chip, 15K, 1/8W, 1%, 0603
21	1	R8	Resistor	Resistor	Std	1k	603		Resistor, Chip, 1K, 1/8W, 1%, 0603
22	1	R11	Resistor	Resistor	Std	NA	805		Resistor, Chip, 2K, 1/5W, 1%, 0805
23	1	R31	Resistor	Resistor	Std	2K	805		Resistor, Chip, 2K, 1/5W, 1%, 0805
24	1	Q1	MOSFET	Si7810DN	Vishay	5A,100V	POWERPAK		MOSFET, N-ch, Si7810DN, POWERPAK 1212

25 8 14V5 15V GND RTN TP1-2 VIN VIN_GND

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